

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
 For capacitive load, derate current by 20%.

Characteristic	Symbol	DFLR1200	DFLR1400	DFLR1600	Units
Peak Repetitive Reverse Voltage	V _{RRM}				
Working Peak Reverse Voltage	V _{RWM}	200	400	600	V
DC Blocking Voltage	V _R				
RMS Reverse Voltage	V _{R(RMS)}	140	280	420	V
Average Rectified Output Current (see figure 4)	I _O	1.0			A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	25			A

Thermal Characteristics

Characteristic	Symbol	Typ	Max	Unit
Thermal Resistance, Junction to Ambient Air (Note 6)	R _{θJA}	134	—	mW
Thermal Resistance, Junction to Soldering Point (Note 7)	R _{θJS}	—	6	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	—	-65 to +150	°C

Electrical Characteristic (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Forward Voltage @ I _F = 1.0A	V _{FM}	1.1	V
Peak Reverse Leakage Current @ T _A = +25°C	I _{RM}	3.0	μA
at Rated DC Blocking Voltage @ T _A = +125°C		100	
Typical Total Capacitance (f = 1MHz, V _R = 4.0VDC)	C _T	10	pF

Notes: 6. Device mounted on 1" x 1", FR-4 PCB; 2 oz. Cu pad layout as shown on Diodes Inc. suggested pad layout document AP02001.pdf. T_A = +25°C
 7. Theoretical R_{θJS} calculated from the top center of the die straight down to the PCB/cathode tab solder junction.

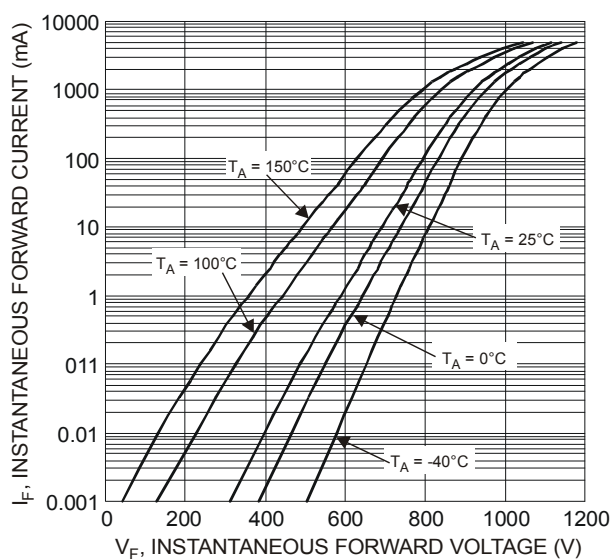


Figure 1 Typical Forward Characteristics

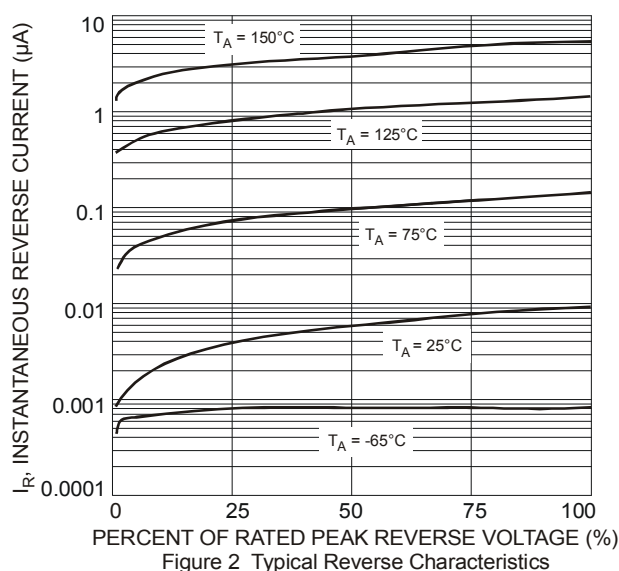


Figure 2 Typical Reverse Characteristics

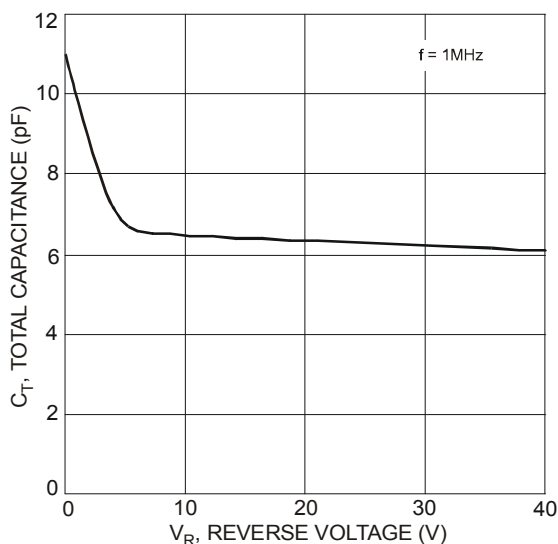


Figure 3 Typical Total Capacitance

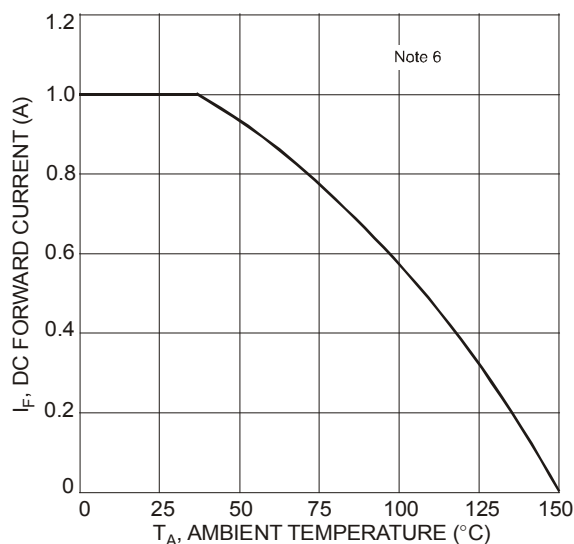
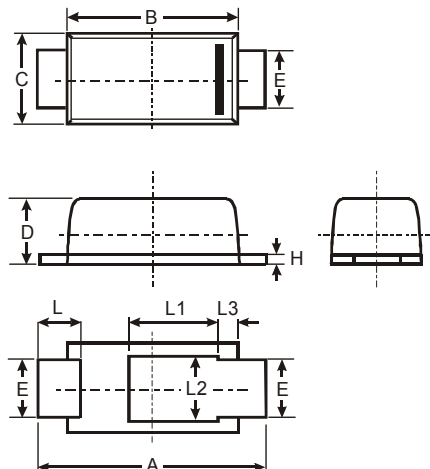


Figure 4 DC Forward Current Derating

Package Outline Dimensions

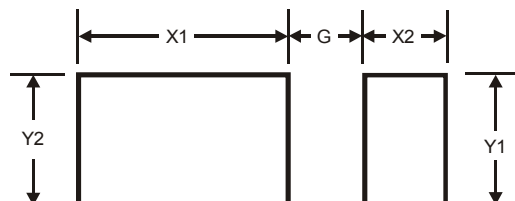
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



POWERDI [®] 123			
Dim	Min	Max	Typ
A	3.50	3.90	3.70
B	2.60	3.00	2.80
C	1.63	1.93	1.78
D	0.93	1.00	0.98
E	0.85	1.25	1.00
H	0.15	0.25	0.20
L	0.40	0.50	0.45
L1	-	-	1.35
L2	-	-	1.10
L3	-	-	0.20
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
G	1.0
X1	2.2
X2	0.9
Y1	1.4
Y2	1.4

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